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Standard Practice for Preparation of Aerospace Contamination Control Plans¹

This standard is issued under the fixed designation E1548; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ε) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This practice is intended to assist in the preparation of formal plans for contamination control, especially of aerospace critical surfaces. Requirements may be established at the systems level, either by the customer or the systems integrator, or at the subsystem level. Subsystem requirements may be imposed by the responsible subsystem supplier or they may be flowed down from the systems organization (4.7). The extent of detail and level of cleanliness required can vary with the particular application and type of hardware being built, but all aspects of contamination control must be included in a final plan. Therefore, each of the following elements must be considered for inclusion in a contamination control plan (CCP):

1.1.1 *Cleanliness requirements* for deliverable hardware addressing particulate, molecular, or biological contaminants or combination thereof. Specify contamination limits and any budget allocations.

1.1.2 *Implementation plans* to achieve, verify, and maintain the specified cleanliness requirements. Specify material and process controls, cleaning techniques, verification tests, protection and prevention plans, transportation controls, and corrective action for discrepancies.

1.1.3 Environmental controls including clean facilities to be used, facility maintenance, and monitoring schedule.

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1.1.4 *Personnel and operational controls* including operating procedures, restrictions, training, motivation, and organizational responsibilities including the organization or individual for implementation and verification of the CCP.

1.2 The values stated in SI units are to be regarded as standard. No other units of measurement are included in this standard.

1.3 This international standard was developed in accordance with internationally recognized principles on standardization established in the Decision on Principles for the Development of International Standards, Guides and Recommendations issued by the World Trade Organization Technical Barriers to Trade (TBT) Committee.

2. Referenced Documents

2.1 ASTM Standards:²

E595 Test Method for Total Mass Loss and Collected Volatile Condensable Materials from Outgassing in a Vacuum Environment

E1216 Practice for Sampling for Particulate Contamination by Tape Lift

¹This practice is under the jurisdiction of ASTM Committee E21 on Space Simulation and Applications of Space Technology and is the direct responsibility of Subcommittee E21.05 on Contamination.

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² For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For Annual Book of ASTM Standards volume information, refer to the standard's Document Summary page on the ASTM website.



2.4 IEST Standards:⁶

IEST-STD-CC1246DIEST-STD-CC1246E Product Cleanliness Levels and Contamination Control Program

NOTE 1-The Institute of Environmental Sciences has several Recommended Practices which may also be useful in the preparation of a CCP.

3. Terminology

3.1 *Definitions:*

- 3.1.1 *bidirectional reflectance distribution function (BRDF)*—(*BRDF)*, *n*—the scattering properties of light reflected off surfaces, expressed as the ratio of differential outputs of radiance divided by differential inputs of radiance. Surface contaminants scatter the incident radiation in all directions and with variable intensities; BRDF is a method to quantify the spatial distribution of the scattered energy.
- 3.1.2 *biological contamination*<u>contamination</u>, <u>n</u>living material such as algae, bacteria, fungus, and so forth, which is capable of reproducing, thus being an increasing contaminant source.
- 3.1.3 *budget allocation—allocation, n*—the itemized summary of contamination accumulation for a given critical hardware item distributed over all phases from manufacture through end of performance lifetime.
- 3.1.4 *cleanroom*—*cleanroom*, *n*—an environmentally conditioned area where temperature, humidity, and airborne contaminants are controlled by design and operation. High Efficiency Particulate Air (HEPA) filters or better are usually required to achieve the air cleanliness level. Air particulate cleanliness is classified in accordance with ISO 14644-1.
- 3.1.4.1 *as-built <u>cleanroom</u>_<u>cleanroom</u>, <u>n</u>_a cleanroom that is complete and ready for operation, with all services connected and functional, but without equipment or operating personnel in the cleanroom.*
- 3.1.4.2 *at-rest <u>cleanroom</u>_<u>cleanroom</u>, <u>n</u>_a cleanroom that is complete and ready for operation, with all services connected and functional, and with equipment installed and operable, as specified but without operating personnel in the cleanroom.*
- 3.1.4.3 *operational <u>cleanroom</u>_<u>cleanroom</u>, <u>n</u>_a cleanroom in normal operation, with all services functioning and with equipment and personnel, if applicable, present and performing their normal work functions in the cleanroom.*

³ Available from Standardization Documents Order Desk, Bldg. 4 Section D, 700 Robbins Ave., Philadelphia, PA 19111-5094, Attn: NPODS.

⁴ FED-STD-209 has been superceded by ISO 14644-1 and -2. It may continue to be used if mutually agreed to by customer and supplier.

⁵ Available from American National Standards Institute (ANSI), 25 W. 43rd St., 4th Floor, New York, NY 10036, http://www.ansi.org.

⁶ Available from Institute of Environmental Sciences and Technology (IEST), Arlington Place One, 2340 S. Arlington Heights Rd., Suite 100, Arlington Heights, IL 60005-4516, http://www.iest.org.



NOTE 2-For batch operations, specific conditions and requirements should be noted for monitoring and control.

3.1.5 *clean zone_zone, n*_a defined space in which the concentration of airborne particles is controlled to meet a specified airborne particulate cleanliness class.

3.1.6 *controlled area*<u>area</u>, <u>n</u><u>an</u> area which does not require a high degree of temperature and humidity control but a semi-clean atmosphere is desired. Air conditioning is standard commercial design except that filtration is rated to $\frac{80-85\%}{80\%}$ to $\frac{80\%}{10}$ to $\frac{85\%}{10}$ for 1.0 micrometer (µm) and larger particles to control airborne contaminants. These areas shall not exceed the airborne particle concentration of Class 8.5 (FED-STD-209E Class 300,000) at 0.5 µm and Class 8 (Class 100,000) at 5.0 µm per ISO 14644-1 (FED-STD-209E). Reference USAF Tech Order 00-25-203.

3.1.7 *facility—facility, n*—the total real property required to accomplish the environmental control and operation of cleanrooms, clean zones, and controlled areas as well as administrative and personnel support.

NOTE 3-This includes the cleanroom proper, air locks, change rooms, parts cleaning, storage, HVAC equipment, offices, and so forth.

- 3.1.8 HVAC-HVAC, n-Heating, Ventilating, and Air Conditioning.
- 3.1.9 *image analysis*—<u>analysis</u>, <u>v</u>—the measurement of size, shape, number, position, orientation, brightness, and other parameters of small objects using the combination of an autofocusing microscope, an imaging sensor, and a dedicated computer system. Can be used to perform particle counts or measure particle dimensions automatically, with far greater accuracy than manual techniques.
- 3.1.10 *molecular contamination*<u>contamination</u>, <u>n</u>_nonparticulate matter in the form of droplets or thin films which adversely affects component or system performance.
- 3.1.11 *nonvolatile residue* (*NVR*)—(*NVR*), *n*—soluble material remaining after evaporation of a filtered volatile fluid or precipitate from a gas phase, usually reported in milligrams per unit area (or volume).

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3.1.12 *particulate contamination*—*contamination*, *n*—small discrete mass of solid matter, usually measured in micrometers (µm), which adversely affects component or system performance.

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- 3.1.13 precision <u>cleaning—cleaning, v</u>cleaning of hardware surfaces by approved engineering methods to meet specific cleanliness criteria.
- 3.1.14 *visibly <u>clean</u>*-<u>clean, n</u>-absence of particulate or molecular contaminants when viewed from a specified distance with normal (or corrected to normal) vision with a specified illumination level.

4. Contents of CCP

4.1 General Items and Information:

4.1.1 All CCPs shall include an introduction or scope specifying the contamination-sensitive component(s) or system(s) being addressed, a list of applicable documents, and a list of definitions including any acronyms and abbreviations used in the document.

4.1.2 The level of detail required and the nature and extent of controls needed depends upon a number of factors. The systems organization or systems integrator has a better overview of contamination limitations, sensitivity of specific components and hardware, and total mission requirements than sub-tier suppliers. Contamination limits for total systems are the primary responsibility of the systems organization. Final contamination limits at delivery of the integrated system and at end of life should be established by agreement between the purchaser and systems supplier. Each supplier is responsible for defining and controlling the contamination level of the particular hardware being supplied, with the approval of the systems organization, in addition to requirements levied by the systems integrator.

4.1.3 The buyer and seller should agree on the contents and implementation of the CCP before any parts are processed beyond the first cleaning or inspection point. Suppliers of subsystems and components should prepare Contamination Control Plans so that the functional requirements of the hardware are protected. If a subsystem is particularly sensitive to contamination, there must be